

Day : Saturday
 Date: 7/24/2004

Time: 13:47:12

PALM INTRANET**Inventor Name Search Result**

Your Search was:

Last Name = ONITSUKA

First Name = YASUTO

Application#	Patent#	Status	Date Filed	Title	Inventor Name 9
10697581	Not Issued	030	10/30/2003	BONDING METHOD	ONITSUKA, YASUTO
10635314	Not Issued	020	08/06/2003	TRANSFER CARRIER FOR FLEXIBLE PRINTED CIRCUIT BOARD AND ELECTRONIC PARTS MOUNTING METHOD TO FLEXIBLE PRINTED CIRCUIT BOARD	ONITSUKA, YASUTO
09877112	6618937	150	06/11/2001	A METHOD OF ASSEMBLING ELECTRONIC APPLICATIONS AND DISPLAY DEVICES	ONITSUKA, YASUTO
08718974	5839645	150	09/26/1996	BONDING MACHINE OF ELECTRONIC COMPONENTS AND BONDING METHOD THEREOF	ONITSUKA , YASUTO
08429871	5628660	150	04/27/1995	BONDING APPARATUS AND BONDING METHOD OF DEVICES	ONITSUKA , YASUTO
08341095	5513792	150	11/17/1994	BONDING APPARATUS	ONITSUKA , YASUTO
08338413	5591295	150	11/14/1994	BONDING APPARATUS FOR ELECTRONIC COMPONENTS	ONITSUKA , YASUTO
08313595	5501005	150	09/29/1994	MOUNTING DEVICE OF ELECTRONIC COMPONENTS AND A MOUNTING METHOD	ONITSUKA , YASUTO
08299766	5501004	150	09/01/1994	OUTER-LEAD BONDING APPARATUS AND METHOD THEREFOR	ONITSUKA , YASUTO

Inventor Search Completed: No Records to Display.

Search Another: Inventor

Last Name	First Name
<input type="text" value="ONITSUKA"/>	<input type="text" value="YASUTO"/>
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L Number	Hits	Search Text	DB	Time stamp
1	88	((press or pressure) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04
2	1	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and (position or positioning) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:50
3	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and (position or positioning) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:50
4	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("XY" near4 table) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
5	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("XY" near4 table) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
6	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y" near4 table) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
7	0	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y" near4 table) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
9	1	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y") and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 13:51
8	1	((press or pressure) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y") and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04
10	2	((head) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y") and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04
11	8	((head) near4 (bond or bonding or bonder)) and (optical near2 camera) and ("X Y") and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04
12	79	((head) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (29/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:04

13	39	((head) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/24 14:05
-	879	(ACF or anisotropic) and (tape or film) and (156/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:08
-	1 1207	("20040129364").PN. (156/64).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 16:54
-	2	("6596115").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 13:14
-	1 2225	("6544377").PN. (29/832).CCLS.	USPAT USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 13:22 2004/07/22 21:13
-	403	(29/833).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	461	(29/834).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	283	(29/738).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	1985	(29/739).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:13
-	198	(156/539).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 18:34
-	104	(29/836).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/22 21:26
-	514	(156/538).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 15:12
-	0	2003-59975	JPO	2004/07/23 15:12
-	0	"59975"	JPO	2004/07/23 15:12

-	10	yasuto.in. near3 onitsuka.in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 15:24
-	1244	(29/740).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 15:25
-	0	yasuto.in. and onitsuka.in.	JPO	2004/07/23 15:25
-	0	yasuto and onitsuka	JPO	2004/07/23 15:25
-	0	6618937.URPN.	USPAT	2004/07/23 16:45
-	5	("5495661" "5727311" "5894657" "6086641" "6140707").PN.	USPAT	2004/07/23 16:45
-	1	("20010032030").PN.	US-PGPUB	2004/07/23 16:54
-	364	(156/358).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 18:34
-	214	(156/360).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 18:34
-	815	(156/361).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 18:34
-	288	(156/362).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:06
-	826	(156/297).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:06
-	623	(156/299).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:06
-	414	(156/300).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:06
-	1041	(ACF or anisotropic) and (tape or film) and (29/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:08
-	6	(plural near2 board) and (detect or detecting) and (position or positioning) and (156/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 21:09

-	10	((plural near2 board) and (detect or detecting) and (position or positioning) and (29/\$.ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 19:12
-	228	((press or pressure) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (156/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 21:10
-	139	((press or pressure) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (29/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 21:10
-	102	((press or pressure) near4 (bond or bonding or bonder)) and (detect or detecting) and (position or positioning) and (156/\$.ccls.) and (tape or chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/23 21:10